

L Number	Hits	Search Text	DB	Time stamp
7	518	(257/59, 72, 762, 751, "753").ccls. and @py>2001	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/15 10:46
8	523	(438/149, 151, 157, 163, 161, "166").ccls. and @py>2001	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/15 10:43
9	2349	(349/42-45, "116").ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/15 10:43
10	5862	(438/30, 149-166).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/15 10:45
11	5361	(257/59-72, 762, 751, "753").ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/15 10:46
12	12862	((349/42-45, "116").ccls.) or ((438/30, 149-166).ccls.) or ((257/59-72, 762, 751, "753").ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/15 10:47
13	301	((349/42-45, "116").ccls.) or ((438/30, 149-166).ccls.) or ((257/59-72, 762, 751, "753").ccls.) and ((cu or copper) with (Ti or titanium)) and (display or TFT or TFTs or (thin adj film adj transistor\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/15 14:07
14	4054	((cu or copper) with (Ti or titanium)) and (display or TFT or TFTs or (thin adj film adj transistor\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/15 14:08
15	1252	((cu or copper) with (Ti or titanium)) and (display or TFT or TFTs or (thin adj film adj transistor\$1)) and (TiO\$6 or ((Ti or Titanium) near oxide))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/15 15:38
16	20	((cu or copper) with (Ti or titanium)) and (display or TFT or TFTs or (thin adj film adj transistor\$1)) and ((corrosi\$4 or barrier or adhens\$4) with (TiO\$6 or ((Ti or Titanium) near oxide)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/15 13:43
17	12	(gate with (cu or copper)) and ((corrosi\$4 or barrier or adhens\$4) with (TiO\$6 or ((Ti or Titanium) near oxide)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/15 13:43
18	1	JP10153788\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/15 13:41
19	2	10153788\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/15 13:42

20	2	"3302894"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/15 13:43
21	10	((cu or copper) near2 (wiring or gate or wire)) with (Ti or TiO\$5) with adhesion	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/15 14:38
22	238	((cu or copper) near2 (wiring or gate or wire)) with (Ti or TiO\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/15 14:04
23	19	((cu or copper) near2 (wiring or gate or wire)) and (Ti with TiO\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/15 14:07
24	30922	((cu or copper) near2 (wiring or gate or wire))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/15 14:33
25	2812	((cu or copper) near2 (wiring or gate or wire))) and (display or TFT or TFTs or (thin adj film adj transistor\$1))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/15 14:08
26	394	((cu or copper) near2 (wiring or gate or wire))) and (display or TFT or TFTs or (thin adj film adj transistor\$1)) and (Ti or titanium or TIO\$6)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/15 14:09
27	10	((cu or copper) near2 (wiring or gate or wire))) and ((Ti or Titanium) with anodiz\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/15 14:34
28	280	(cu or copper) and ((Ti or Titanium) with anodiz\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/15 14:35
29	126	((cu or copper) and ((Ti or Titanium) with anodiz\$5)) and (gate or interconnect\$5 or wir\$5)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/15 14:36
30	1147	((cu or copper) near2 (wiring or gate or wire)) and (TiO\$5 or ((Ti or Titanium) with oxid\$7))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/15 14:52
31	1148	((cu or copper) near2 (wiring or gate or wire)) and (TiO\$5 or ((Ti or Titanium) with (oxide\$1 or oxidat\$4)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/15 14:53
32	125	((cu or copper) near2 (wiring or gate or wire)) and (TiO\$5 or ((Ti or Titanium) with (oxide\$1 or oxidat\$4)))) and gate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/15 14:45
33	1661	gate with (TiO\$5 or ((Ti or Titanium) with oxid\$7))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/15 15:35

34	2269	(cu or copper) and gate and (TiO\$5 or ((Ti or Titanium) with (oxide\$1 or oxidat\$4)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/15 14:54
35	205	((cu or copper) and gate and (TiO\$5 or ((Ti or Titanium) with (oxide\$1 or oxidat\$4)))) and (((349/42-45, "116").ccls.) or ((438/30, 149-166).ccls.) or ((257/59-72, 762, 751, "753").ccls.))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/15 15:28
36	1364	gate with anodic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/15 15:29
37	79	(gate with anodic) and (gate with (TiO\$5 or ((Ti or Titanium) with oxid\$7)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/15 15:29
38	68	gate with (TiO\$5 or ((Ti or Titanium) with oxid\$7)) with (covered or coated)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/15 15:37
39	2580	438/158.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/15 15:47
40	31	438/158.ccls. and (TiO\$6 or ((Ti or Titanium) near oxide))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/15 15:56
41	11	5334544.URPN.	USPAT	2002/11/15 15:41
42	27	438/158.ccls. and (gate with (Cu or copper))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/15 15:53
43	56	"5166085"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/15 15:54
44	64	438/158.ccls. and (TiO\$6 or ((Ti or Titanium) with oxid\$5))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/15 15:57
45	33	(438/158.ccls. and (TiO\$6 or ((Ti or Titanium) with oxid\$5))) not (438/158.ccls. and (TiO\$6 or ((Ti or Titanium) near oxide)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/15 15:57
-	9	((cu or copper) near2 (wiring or wire)) with Tin with adhesion	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/11/15 13:44